



PMEG3010EB

1 A very low V_F MEGA Schottky barrier rectifier

Rev. 01 — 1 December 2006

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD523 (SC-79) ultra small and flat lead Surface-Mounted Device (SMD) plastic package.

1.2 Features

- Forward current: $I_F \leq 1$ A
- Reverse voltage: $V_R \leq 30$ V
- Very low forward voltage
- Ultra small and flat lead SMD plastic package

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications

1.4 Quick reference data


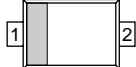
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current	$T_{sp} \leq 55$ °C	-	-	1	A
V_R	reverse voltage		-	-	30	V
V_F	forward voltage	$I_F = 1$ A	[1] -	610	680	mV

[1] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	cathode	[1]	 sym001
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG3010EB	SC-79	plastic surface-mounted package; 2 leads	SOD523

4. Marking

Table 4. Marking codes

Type number	Marking code
PMEG3010EB	KA

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	30	V
I_F	forward current	$T_{sp} \leq 55\text{ °C}$	-	1	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms};$ $\delta \leq 0.25$	-	1	A
I_{FSM}	non-repetitive peak forward current	square wave; $t_p = 8\text{ ms}$	-	3	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]	310	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	400	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[3]	-	-	75	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Soldering point of cathode tab.

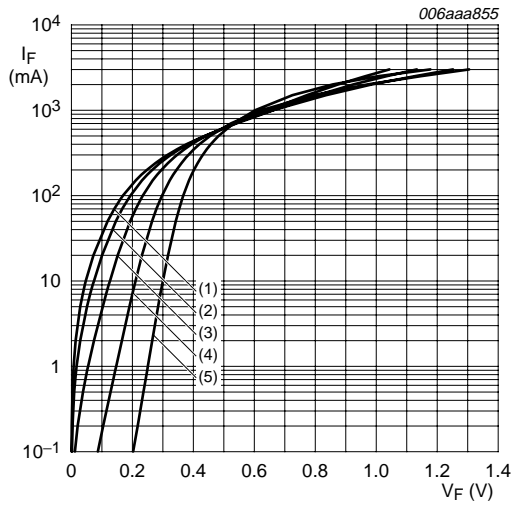
7. Characteristics

Table 7. Characteristics

$T_{amb} = 25\text{ }^\circ\text{C}$ unless otherwise specified.

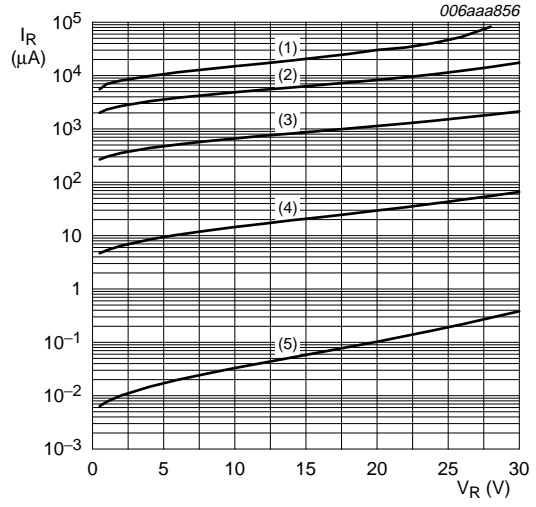
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage		[1]			
		$I_F = 0.1\text{ mA}$	-	90	180	mV
		$I_F = 1\text{ mA}$	-	150	200	mV
		$I_F = 10\text{ mA}$	-	210	270	mV
		$I_F = 100\text{ mA}$	-	295	360	mV
		$I_F = 500\text{ mA}$	-	430	500	mV
		$I_F = 1\text{ A}$	-	610	680	mV
I_R	reverse current	$V_R = 10\text{ V}$	-	15	200	μA
		$V_R = 30\text{ V}$	-	70	500	μA
C_d	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$	-	24	30	pF

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.



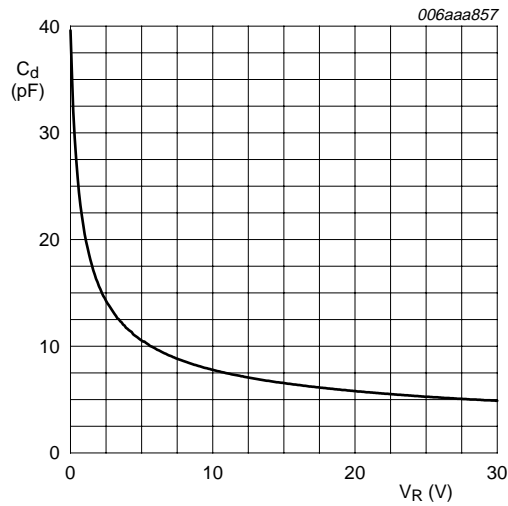
- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 125\text{ °C}$
- (3) $T_{amb} = 85\text{ °C}$
- (4) $T_{amb} = 25\text{ °C}$
- (5) $T_{amb} = -40\text{ °C}$

Fig 1. Forward current as a function of forward voltage; typical values



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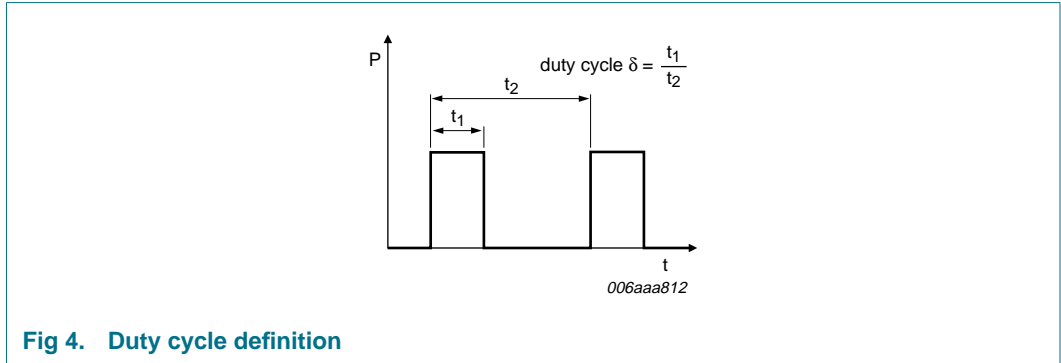
Fig 2. Reverse current as a function of reverse voltage; typical values



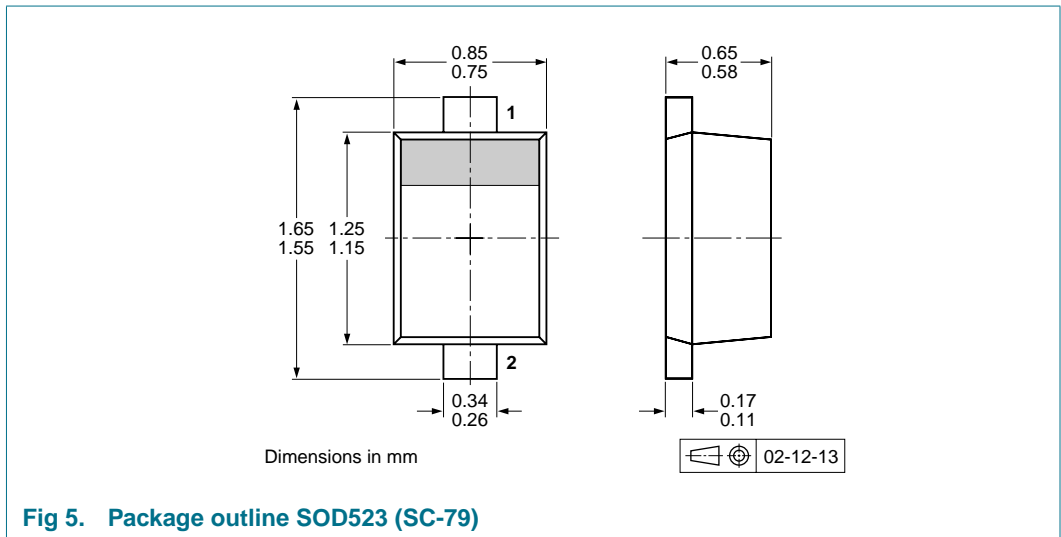
$f = 1\text{ MHz}$; $T_{amb} = 25\text{ °C}$

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Test information



9. Package outline



10. Packing information

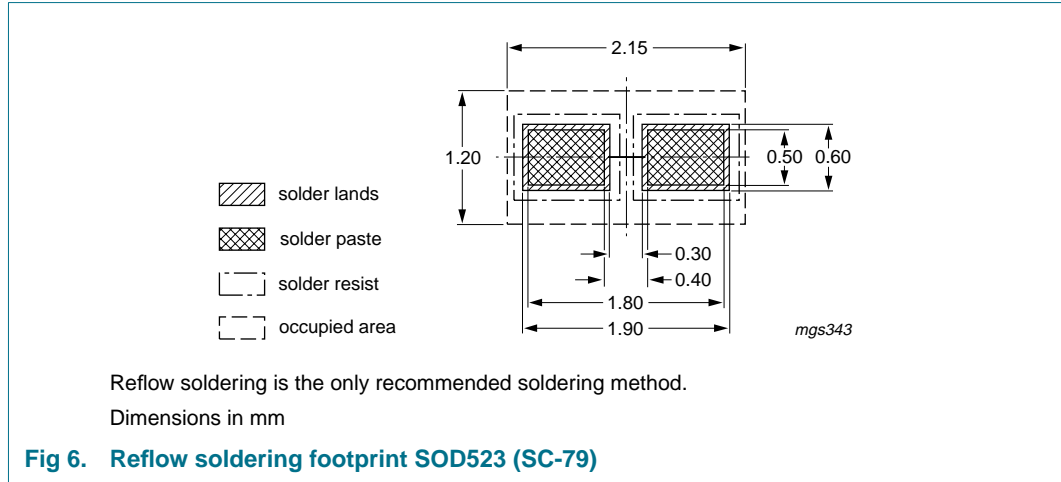
Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity		
			3000	8000	10000
PMEG3010EB	SOD523	2 mm pitch, 8 mm tape and reel	-	-315	-
		4 mm pitch, 8 mm tape and reel	-115	-	-135

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3010EB_1	20061201	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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